DOCUMENT: M21372 REV LETTER: A PAGE NO: 1 OF 2 REV DATE: 2022-6-7 PART NUMBER: LP-NSML350HF Surface Mount Thermistor			es r	Wayon Electronics Co., Ltd. Wayon Shanghai 201202, P.R.China No.1001, Shiwan 7th Road, Pudong, Shanghai 201202, P.R.China Tel: 86-21-50968308 Fax: 86-21-50968310 E-mail: market@way-on.com Http://www.way-on.com						
 Features Small size 1206 Low resistance Lead-free and compliant with the European Union RoHS Directive (EU)2015/863 Fast time-to-trip Agency Recognition: UL \ TUV 										
Product Dimension (mm)										
Part Number	A Typ.		В Гур.	C Typ.	D Typ		E Typ.	Part Marking	5	E
LP-NSML350HF	3.30±0.			0.40±0.20			30±0.20	E		
Electrical Characteristics Maximum Electrical Rating • Operating Voltage: 6 Vdc • Interrupt Current: 50 A										
PART NUMBER	HOLD CURRENT & TRIP CURR (AMPS)			CURRENT	TIME-TO-TRIP (SECONDS)		REFERENCE RESISTANCE (OHMS)		TRIPPED STATE POWER DISSIPATION (WATTS)	
	25°C		6	o⁰C	17.5 A @ 25°C		25°C		25°C,6V	
LP-NSML350HF	Hold	Trip	Hold	Trip	Min.	Max.	Min.	Max. *	Μ	lax.
	3.5	7.0	2.4	4.8	-	5.0	0.004	0.018	1	.5
Thermal Dera	Thermal Derating									
LP-NSML350HF	40			Aaximum an						
Hold Current (A)	-40 4.70	-20 4.10	0 3.80	20 3.55	25 3.50	40 2.90	50 2.60	60 2.40	70 2.00	85 1.40
Trip Current (A)	9.40	8.20	7.60	7.10	7.00	5.80			4.00	2.80
•	*Values specified were determined using the PWB with 2.7mm*1.0oz copper traces. Solder Reflow Recommendation Solder Pad Layout									
	с	1/4 C			Part Nui		A (mm) 1.75	B (mm) 1.15		C (mm) 1.60
								cil Window		
PCB Solder Pad	1 	B A				t Number		<u> </u>	B (mm)	C (mm)
260°C		→	← 20-40s			ISML350H ended refle		<u>1.95</u> s: IR, vapor p	1.15 bhase, hot	1.60 air oven.
217C 200C 150C	Ramp-up	60-1508		n Pa Ta Ef	devices r Devices side of th ackage I ape & Ree ffectivity:	may not m are not de ne board. nformati el: 4000pc	eet the per signed to b on s per reel. documents	the recommend formance rec e wave solde s shall be the	quirements ered to the	s. e bottom

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame.

25°C

- 8 minutes max.

Average Ramp-Up Rate:3ºC/second max.

. Time

Ramp-Down Rate:6 °C /second max.

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DOCUMENT: M REV LETTER: A PAGE NO: 2 OF REV DATE: 202 PART NUMBER	Polymer 2-6-7 E PTC Devices	Wayon Electronics Co., Ltd. No.1001, Shiwan 7th Road, Pudong, Shanghai 201202, P.R.China Tel: 86-21-50968308 Fax: 86-21-50968310						
LP-NSML35	OHF Surface Mount Thermistor	E-mail: <u>market@way-on.com</u> Http://www.way-on.com						
	SMD PTC 使用注意事项							
	Caut	ions for SMD PTC Use						
阻值升高。	甚至烧片。	超出 PTC 最大电压或最大电流规格值的操作,可能会导致 PTC 出现电弧,						
2. 规格书所; 下保持1 Hold curre welding. F	舰定的各温度下的 Hold current 均是 I 小时。该电流并不是该型号 PTC 能够 ent at all temperatures specified in th PTC can hold 1 hour under current co	e SPEC is the conventional performance of PTC obtained by one time reflow onditions at a given temperature. This current is not the condition of long-term						
3. 规格书所:	or discharging current for this type of 舰定的电阻以及电气特性,均是基于很 其他热工序,会对上述参数有一定程用	车维安指定测试板经过一次回流焊之后的测试。如果客户有二次回流焊或者注						
The abov generated certain de	e parameters are concluded from on I process like injection or dispensing gree. Therefore the verification test t	e time of reflow soldering processing the PTC. If there is any further heat at the customer's premise, the aforementioned parameters will decrease at						
The PTC	is thermal sensitive device. It is reco	mmended not to design any heat source devices around it to reduce the						
5. PTC 贴片 度超过推 SMD PTC	荸的值,PTC 将有可能受到损伤。禁 辩 is designed for SMT processing wh	焊接工艺为回流焊。焊接工艺可参考维安推荐的回流焊曲线。如果回流焊温 止使用手工焊接 PTC,禁止对线路板其他元件或端子返工时使用热风枪。 ich applies reflow soldering. Please refer to the Wayon recommended curve ire exceeds the recommended value, the PTC might be damaged. Hand						
 PTC 贴装 参数(如) 	或应用过程中,所使用到的各类注塑料 揾度、时间等)进行验证,以确保产品。	wed to use during the circuit board components or terminals rework. 、单组份、双组份固化胶粘剂、硅胶,需要对注塑料胶料等材料牌号以及应用 品及工艺的匹配性,确认不会影响 PTC 性能之后方可使用。						
solvents r		Iding materials, curing adhesives, UV glue , silica gel and cleaning agents or parameters e.g. temperature, time, and etc to ensure the consistency e use.						
 PTC 贴装 适用性, 等较强溶/ When mo is required that they benzene 	或使用过程中,不建议使用洗板水或 确认不会影响 PTC 性能之后方可使用 解性、破坏性的有机化合物。清洗后料 unting or using PTC, it is not recomn d, it is necessary to verify the applica will not affect the PTC performance. nomolog, ketones, lipids and derivate	其他清洗剂进行清洗。如必须使用,需要验证各类清洗剂、洗板水以及溶剂的 。已知对 PTC 有影响的化学药品包括但不仅限于醚类、苯类、酮类以及脂类 将产品放置于敞开的环境中至少 24 小时,将残留的溶剂进行充分的挥发。 nended to use circuit board washer water or other cleaning agent. If cleaning ibility of various cleaning agents, washboard water and solvents, and confirm The known chemicals that impacts PTC include but not limited to ethers, es that is of strong solubleness and ruinous. Please place the product in						
8. 装配过程		tilize solvents residuals. . 刺等方式作用 PTC 本体,以免引起 PTC 性能衰减。 t by tool during assembling process otherwise it might be a cause of the						
	nce degradation.	t by tool during assembling process otherwise it might be a cause of the						
则需密闭	呆存,可避免 PTC 长时间暴露于空气							
time as po environme	ossible. If the time slot between mounter to avoid long air exposure.	oplication, if injection or gluing is needed, it should be completed in as short a nting and injection or gluing surpasses 1 month,, please keep in airtight						
	settable protection device which shal	用,重复多次的保护会降低 PTC 的维持电流。 Il not be taken for use as switch. Multiple times tripping shall lower the PTC						
11. PTC 在充 In chargir	电线端应用中,建议使用 PP 类材料(做内膜,禁止使用 TPE 类与 PVC 类等材料做内膜。 rial is recommended to use as inner membrane and TPE and PVC type						
12. PTC 在加 的接触时 In the pro be more	工过程中,如有烙铁焊接工艺,建议: 可不超过 3sec。 cess of PTC processing, if there is so than 1.5mm away from PTC, the wel	焊接位置距离 PTC 1.5mm 以上,焊接工具温度低于 350°C,焊接铁头与焊点 oldering iron welding process, it is suggested that the welding position should lding tool temperature should be lower than 350°C, and the contact time bet						
13. 维安低阻 余料,需 Wayon lo ^v stock, the	灰复之前包装状态,做密封保存。 w resistance SMD PTC humidity sens y should isolate the product immedia	t exceed 3sec. 包装。客户如在库存中发现有包装破损的,立即将产品隔离处理;使用时如有 sitivity grade 2, for sealed packaging. If customers find damaged packaging in ately; if there is surplus material, they need to restore the packaging status,						
14. 产品报废F When the		去律法规回收报废,具体原材料组成可参见 MSDS。 e treated recycled in accordance with local laws and regulations, and raw d to MSDS.						
Specifica	tions are subject to change without n	notice. Page 2 of 2						

Specifications are subject to change without notice.